

LEX 2

The LEX 2 is an accurate and reasonably priced micro-focus X-ray inspection tool for off line examination of electromechanical and microelectronic components. Reliable, delivering high magnification, multi-angle examination, and large-area inspection

Parameters

Dimension	L1360mm×W1240mm×H1700mm
Power Supply	220V 10A/110V 15A 50-60HZ
Max Sample Size	540mm×440mm
OS	IPC WIN7/ WIN10 64 bit
N.W.	About 1170KG

FUNCTION OVERVIEW

- All-purpose model for general x-ray inspection.
- Quick capture of High-Definition pictures.
- Fast infrared auto-positioning and navigation.
- CNC multipoint array automated inspection mode.
- Simple defects detection in tilt and multi-angle modes.
- Software that is easy to use and requires little training, saving money.
- Together, the X-ray tub and FPD support rotation (0–60°) to provide an understandable and crisp image.

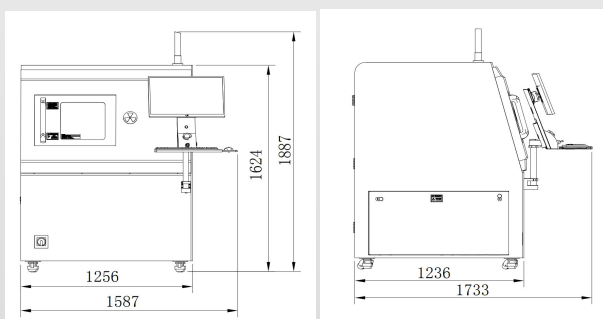
X-ray Tube Spec

Tube Type	Reflective sealed micro-focus ray source
Tube Voltage	40-90KV
Tube Current	10-200 μA/10-300 μA
Max Output Power	8 W/39W
Micro Focus Size	5~15μm

FPD Spec

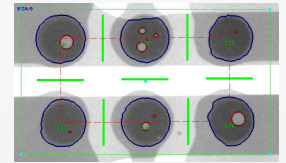
Detector Type	Amorphous silicon flat panel detector
Pixel Matrix	1536×1536
FOV	130mm×130mm
Resolution	5.8Lp/mm
Image frame rate (1×1)	20fps
AD conversion digits	16bit

Dimensions



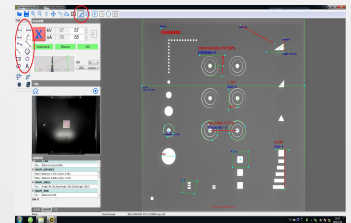
Automatic void ratio calculation

•Enhanced BGA detection feature that allows for fast ball selection, marking, and examination of one or more balls in a matrix frame. Complete the examination and identify BGA solder balls either manually or automatically. Easy to use with precise inspection outcomes.



Size measurement

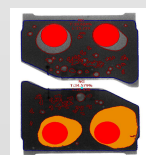
•The following are some examples of measurement tools: text, hand-drawn polygons, hand-drawn free forms, distance, distance ratio, line spacing, angle, arrow mark, circle radius, dot spacing, center distance, and circumference.



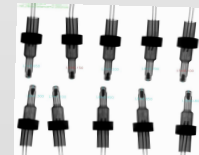
Defects Inspection

•Automatic defect detection: With its customizable imaging algorithms, the LEX 2 is able to recognize size, area disconnection, and tin connection automatically.

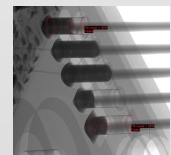
To achieve automatic defect recognition and detection capabilities, unique software algorithms are built based on the features and needs of the customer's product. These algorithms includes presence, crack, disconnection, offset, size, and how many recognition algorithms.



LED pad measurement



Sensor size measurement



THT tin ration measurement